

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITOR Commercial Grade (General Type)

Approved by customer : (signing or stamping here)	

SAMWHA CAPACITOR CO., LTD.						
Writtern by	Checked by Approved by					
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2020. 05. 08.

SAMWHA CAPACITOR CO., LTD.

Address : 124, BUK-RI, NAMSA-MYUN YOUNGIN-SI, KYUNGKI-DO, KOREA

Contact : TEL 82-31-332-6441 , FAX 82-31-332-7661

Home page: www.samwha.com

< SPEC SUMMARY >									
SAMWHA Part no.		CS1005C0G330J500NR							
Type			General						
Item	Specification	pecification Unit Test methods and Conditions(Capacitan							
Capacitance	33	pF							
Capacitance Tolerance	± 5	%	Testing Frequency: 1±0.1Mb Testing Voltage: 1 ±0.2Vrms						
Dissipation Factor	Max. 0.1	%							
Insulation Resistance	More than 10,000	MΩ	Applied the rated voltage for 2 minutes of charging.						
	1.00 ±0.05	L (mm)							
Chip Size	0.50 ±0.05	W (mm)	*Chip size page 2/9						
	0.50 ±0.05	T (mm)	*Characteristics & Test Method page 3/9~6/9						

Enactment :	STANDARD	NO	SW - M - 04B
March 27,1996	MULTILAYER CERAMIC CAPACITOR	Dogo	1 / 0
	Commercial Grade	Page	1 / 9

1. General Article

Application Range

These specifications refer to the "Multilayer Ceramic Capacitors "mainly used to the computer equipment, communication equipment.

*Caution: Industrial equipment / For the high reliability equipment / LED equipment / Etc.

Please contact sales representatives or product engineers before using the products.

(For details, please refer Page 9)

2. General Code

(1) Type Designation

<u>CS</u>	<u>1005</u>	<u>C0G</u>	<u>330</u>	<u>J</u>	<u>500</u>	<u>N</u>	<u>R</u>	_
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Commercial Grade)
- 2) Size Code:

This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

3) Temperature Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class I	C0G	-55 to +125℃	±30 ppm/℃
	X5R	-55 to +85℃	±15%
Class II	X7R	-55 to +125℃	±15%
	Y5V	-30 to +85℃	+22% ~ -82%

4) Capacitance Code(Pico farads):

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero ex) 104 = 100000 pF

R denotes decimal

8R2 = 8.2 pF

5) Capacitance Tolerance Code

Code	Tolerance
В	± 0.1 pF
С	± 0.25 pF
D	± 0.5 pF
F	± 1.0 %
G	± 2.0 %
J	± 5 %
K	± 10 %

Code	Tolerance
М	± 20 %
Р	+ 100, -0%
Z	+ 80, -20%
Н	+ 0.25/-0 pF
I	+ 0/-0.25 pF
U	+ 5/-0 %
V	+ 0/-5 %

6) Voltage Code

code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
\/al	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Vol.	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

7) Termination Code

ex) N: Ni-Sn (Nickel-Tin Plate)

A: Ag/Ni-Sn (Ag Epoxy/Nickel-Tin Plate) -> Soft Termination Type

8) Packing Code

ex) R: 7" Reel Type L: 13" Reel Type B: Bulk Type

9) Thickness option

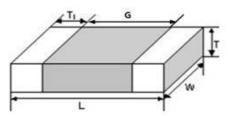
Thickness(mm)		Code	Thickne	Code	
t	Tol(±)	Oode	t	Tol(±)	Oode
0.30	0.03	Blank	1.30	0.20	Е
0.50	0.05	Blank	1.35	0.20	Н
0.60	0.10	А	1.60	0.20	1
0.80	0.10	В	1.80	0.20	J
0.85	0.15	В	2.00	0.25	K
1.00	0.15	Е	2.50	0.25	L
1.10	0.15	Е	2.80	0.30	М
1.15	0.15	Е	3.20	0.30	N
1.25	0.15	Е	5.00	0.40	0

3. Temperature Characteristics

See Page 6/9 (No.14)

4. Constructions and Dimensions

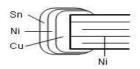
(I) Dimensions



(Unit: mm)

	Dimension						
Code	Ler	gth	Wi	dth	T1 (:)	G(min)	
	L	Tol(±)	W	Tol(±)	T1(min)	G(IIIII)	
0603	0.60	0.03	0.30	0.03	0.05	0.15	
1005	1.00	0.05	0.50	0.05	0.05	0.30	
1608	1.60	0.15	0.80	0.10	0.10	0.50	
2012	2.00	0.20	1.25	0.15	0.10	0.65	
3216	3.20	0.30	1.60	0.20	0.15	1.00	
3225	3.20	0.40	2.50	0.25	0.15	1.05	
4520	4.50	0.40	2.00	0.25	0.20	1.50	
4532	4.50	0.40	3.20	0.30	0.20	1.50	
5750	5.70	0.50	5.00	0.40	0.30	1.85	

(2) Construction of Termination



Specifications	and	Test	Methods	(General)
Specifications	anu	1001	MEHIOUS	(Uclicial)

			Test Methods (d		cificati	on							
No.	Ite	em	Class I Class II							Test Methods and Conditions			
1	Operating Temperature Range)	C0G :-55 to+125℃		X5	R:-5	5 to +1: 5 to +8: 0 to +8:	5℃					
2	Insulation Resistance		More th	nan 10 Vhiche	·Applied the rated voltage for 2 minutes of charging, The charge/discharge current is less than 50mA.								
3	Dielectric St	trength								COG: The rated voltage ×300% X7R, X5R, Y5V: " ×250% - Applied between the terminations for 1 to 5 seconds. - The charge/discharge current is less than 50mA.			
4	Capacitance	Э	within	the s	pecified	d tolera	ance			The capacitance/Q/D.F. should be			
				Char.	50V	25V	16V	10V	6.3V	measured at 25°C at the requency and voltage shown in the table. Cap Testing Testing frequency Voltage COG Testing Testing Voltage COG Testing Testing Frequency Voltage COG Testing Testing Frequency Voltage			
5	5 Dissipation Factor		30pFmin : Q≥1,000(DF≤0.1%) 30pFmax	X7R X5R	min ≤2.5%/ ∗≤5%	≤3%/ *≤7%	≤3.5%/ *≤7%	≤5%/ *≤10%	≤5%/	(C<1000pF)			
			: Q≥400+20C (DF≤1/ (400+20C))	Y5V	≤5%/ *≤9%	≤7%/ *≤9%	≤9%/ *≤12.5%	≤12.5%/ *≤15%	≦15%	· Initial measurement Perform the initial measurement according to Note1 for Class II · Measurement after test Take it out and set it for 24±2 hours (Class I) or			
							24±2 hours (Class II) then measure *Pb-Free type						
6	Solderability Termination		-Termination should be 75% of new solder	-Termination should be covered with more than 75% of new solder						Solder: 96.5Sn-3Ag-0.5Cu Solder temperature: 245±5°C Immersion time: 3±0.1sec *Pre-Heating: at 80~120°C for 10~30sec			
		Appearance	No defects v	vhich	may af	fect p	erforma	nce		Preheat the capacitor at 120 to			
		Capacitance change	within ±2.5% or ±0.25pF (whichever is larger)	X7R Y5V	, X5R: :	≤ ±7 ≤ ±20				150°C for 1 minute. (Preheating for 3225,4520,4532 Step1:100°C to 120°C, 1min			
	Resistance	Dissipation	30pFmin : Q≥1,000 (DF≤0.1%)	Char.	50V min ≤2.5%/	25V ≤3%/	16V ≤3.5%/	10V ≤5%/	6.3V ≤5%/	Step2:170°C to 200°C, 1min) Immerse the capacitor in a eutectic solder solution			
7	to Soldering Heat	Factor	30 _p Fmax : Q≥400+20C	X5R	5R *≤5% *≤7% *≤7% *≤10% *≤1 <5%/ <7%/ ≤9%/ <12.5%/		±576/ *≤10% ≤15%	Soldering Temp:260 ±5°C Immersion Time:10 ±0.5 sec Initial measurement Perform the initial measurement according to Note1 for Class II Immersion Time:10 ±0.5 sec Initial measurement Perform the initial measurement according to Note1 for Class II Immersion Time Time Time Time Time Time Time Time					
		I.R.	(DF≦1/(400+20C)) More th (w		*≦9% D,000MΩ /er is s								

				S	pecifica	tion				_		_						
No.	Item		Class I	Class II									Test Methods and Conditions					
		Appearance	No defects which m	No defects which may affect performance										Perform the five cycles according to the four heat treatments listed in the				
		Capacitance Change	Within ±2.5% or ±0.25pF (whichever is larger)		ving table.		3 Max.	4										
				Char	50V min	25V	16V	10V	6.3V	Temp (°C)	operating temp. +0, -3	Room Temp	operating temp. +3, -0	Room Temp				
8	Temperature Cycle	Dissipation Factor	30pFmin : Q≥1,000 (DF≤0.1%)	X7R X5R	≤5%/ *≤7.5%	≤5%/ *≤10%	≤5%/ *≤10%	≤7.5%/ *≤12.5	≦7.5%/ ∗≤12.5%	Time (min)	30±3	2 to3	30±3	2 to3				
	5,5.5	(or Q)	30pFmax : Q≥400+20C (DF≤1/(400+20C))	Y5V	≤7.5%/ *≤12.5%	≦10%/ *≦12.5%	≤12.5%/ *≤15%	≤15%/ *≤20%	≦20%	Initial measurement Perform the initial measuremen according to Note1 for Class								
More than 10,000MΩ or 500Ω.F (Whichever is smaller) -Measurement after test Perform the final mea according to Note2										easurem	ent							
		Appearance	No defects which m	o defects which may affect performance														
		Capacitance Change	Within $\pm 7.5\%$ or $\pm 0.75 \mathrm{pF}$ (whichever is larger) X7R, X5R : Within $\pm 12.5\%$ Y5V : Within $\pm 30\%$, -40% (Y5V/1.0 μ F,2.2 μ F,4.7 μ F/10V) Within $\pm 30\%$ (others)							-Temperature: 40±2°C ·Humidity: 90~95%RH ·Hour: 500+24/-0 hrs ·Applied Voltage: Rated Voltage The charge/discharge current is								
9	Humidity		30pFmin : Q≥200 (DF≤0.5%)	Char	501/	25V	16V	10V	6.3V	less than 50mA.								
Э	Load	Dissipation Factor(or Q)	30pFmax : Q≥100+10/3C DF≤1/(100+10/3C)	X7R X5R	*≦7.5%	≤5%/ *≤10%	≦5%/ *≦10%	≦7.5%/ ∗≦12.5	≤7.5%/ *≤12.5%	Perfo		ement initial measurement Note1 for Class II						
				Y5V	*≦12.5%			≤15%/ *≤20%	≦20%		easurement after test erform the final measurement							
		I.R	More than $500M\Omega$ or 25Ω .F (Whichever is smaller)								according to Note2							
		Appearance	No defects which m	ay a	ffect pe	rforma	nce			·Testin	g time:	1000+4	18/-0 hrs					
		Capacitance Change	Within ±3% or ±0.3pF (whichever is larger)		X5R : W : Within : Within -	±30% (c +30%, -	ap<1.0	uF)		Rated •Temp	ed voltage d voltage erature :	〈 DC2		00%				
	Le i		30pFmin : Q≥350 (DF≤0.3%)	Chai	50V min	25V	16V	10V	6.3V	The o	G, X7R = 5R, Y5V = charge/dis	→ 85± scharge	3℃					
10	High Temperature Load	Dissipation Factor	10pF ≤ Cp ≤ 30pF : Q ≥ 275+5/2C (DF ≤ 1/(275+5/2C))	X7R X5R	≦5%/	≦5%/ *≤10%	≤5%/ *≤10%	≤7.5%/ *≤12.5	≤7.5%/ *≤12.5%	I laikial was a a suu saa aw	ement	measure	ment					
		(or Q)	10pFmax : Q≥200+10C (DF≤1/(200+10C))	1 Y5V 1		≤10%/ *≤12.5%	≦12.5%/ *≤15%	≤15%/ *≤20%	≦20%	·Meası	ording to	fter te	st					
		I.R			n 1,000 never &					Perform the final measurement according to Note2								

\vdash		Specification											
	No.	lt	em	Class I	- OL	ecilica		ıss II		Test Methods and Conditions			
	11	Bending strength	Capacitance	Substrate material : Glass EPOXY Board. Thickness : 1.6mm 0.8mm(0603/1005size) * Test condition - Bending limit: 1mm - Pressurizing speed : 1mm/sec - Holding time: 5±1sec No cracking or marking defects shall occur Within ±5% or ±0.5pF X7R, X5R: Within ±12.5% (whichever is larger) Y5V: Within ±30%									
-			Change Appearance Capacitance	(whichever is larger) No defects or abnorm Whin the specified to	naliti	es	±30%				*After soldering and then let		
	12 I	Vibration Resistance	Q/DF	30pFmin : Q≥1,000 (DF≤0.1%) 30pFmax : Q≥400+20C (DF≤1/ (400+20C))	Char. X7R X5R	sit for 24±2hr(temperature compensating type), 24±2hr(high dielectric constant type) at room temperature. The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz, shall be traversed(from 10Hz to 55Hz then 10Hz again) in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions(total is 6hours).							
l			Appearance	No defects which ma	y aff	ect pe	rformar	nce					
			Capacitance Change	within ±5% or ±0.5pF (Whichever is larger)			Within ±30%	±12.5%	•		·Temperature : 40±2℃ ·Humidity : 90~95%RH		
		Humidity		30pF min : Q≥350 (DF≤0.3%)	Char	50V min	25V	16V	10V	6.3V	·Hour : 500+24/-0 hrs		
	13	Steady State	Dissipation (or Q)	10pF ≤ Cp ≤ 30pF : Q ≥ 275+5/2C (DF ≤ 1/(275+5/2C))	X7R X5R	≤5%/ *≤7.5%	≤5%/ *≤10%	≤5%/ *≤10%	≦7.5%/ *≦12.5	≦7.5%/ *≦12.5%	Initial measurement Perform the initial measurement according to Note1 for Class II		
10pFmax : Q≥200+10C								Measurement after test Perform the final measurement					
			I.R.				MΩ or 5 smalle				according to Note2		

		Spe					on				Test Methods and Conditions				
No.	Iter	n	(Class	1		Class II				rest methods and Conditions				
14	Capacitance Temperature	Capacitance Change				Char.	Temp Range	Reference Temp.	Cap Change	(1)	Temperature Compensating Type The temperature coefficient is				
	Characteristics					X7R	-55 to +125℃		Within ±15%		determined using the capacit measured in step 3 as a refere When cycling the temperate				
						X5R	-55 to +85℃	25℃	Within ±15%		5,(C0G:	ially from step 1 through +25 to 125°C) the nce shall be with in the			
						Y5V	-30 to +85℃		Within +22% -82%		specified tolerance for the temperature coefficient. The capacitance drift is calculate by dividing the difference betwee the maximum measured values the step 1, 3 and 5 by the cap. value in step 3				
											Step	Temperature(℃)			
				-							1	25±2			
			Пт	emp	Temperature						2	-55±3			
		Temperature	l Char. l		Coefficient						3	25±2			
		Coefficient									4	125±3(for C0G)			
			I I COG I	55 to 125℃	±30 ppm/℃						5	25±2			
											The rang change over value over range sh	ectric Constant Type ges of capacitance compared with the 25°C or the temperature own in the table shall be ecified range.			

*Note1. Initial Measurement for Class II

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure

- *Note2. Measurement after test
 - 1.Class I

Let sit for 24±2 hours at room temperature, then measurement

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure.

5. Packing

- (1) Bulk packing
 - 1 1000 pcs per Polybag
 - 2 5 Polybags per Inner box
 - 3 10 Inner boxes per Out box
- (2) Reel Packing
 - ① 8~10 Reels per Inner box
 - 2 6 Inner boxes per Out box
- (3) Reel Dimensions



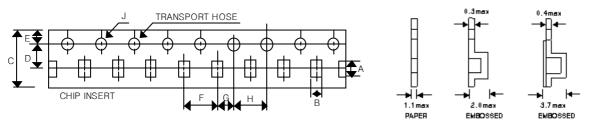


						(L	Jnit: mm)
MARK	SIZE	Α	В	С	D	E	W
7 " REEL	0603~3225	Φ178±2	Ф50Min	Ф13±0.5	Φ21±0.8	2±0.5	10±1.5
/ REEL	4520~4532	Ф180+0,-3	Ф60-0,+1	Φ13±0.2	Ф57-0+1	3±0.2	13±0.5
13 " REEL	1005~3225	Ф330±2	Φ70Min	Ф13±0.5	Φ21±0.8	2±0.5	10±1.5

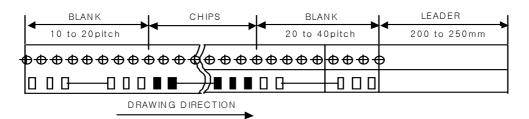
(4) Number of Package

TYPF	EIA CODE	7"	13"
ITE	EIA CODE	Qt/REEL	Qt/REEL
CS0603	CC0201	15,000	
CS1005	CC0402	10,000	50,000
CS1608	CC0603	4,000	15,000
CS2012	CC0805	3,000 ~ 4,000	8,000 ~ 15,000
CS3216	CC1206	2,000 ~ 4,000	6,000 ~ 10,000
CS3225	CC1210	1,000 ~ 3,000	4,000 ~ 10,000
CS4520	CC1808	1,500 ~ 3,000	_
CS4532	CC1812	500 ~ 1,000	1,500 ~ 5,000

(5) Tape Dimensions



TYPE	EIA CODE	А	В	С	D	Е	F	G	Н	J
CS0603	CC0201	0.67±0.05	0.37±0.05	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1005	CC0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1608	CC0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS2012	CC0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3216	CC1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3225	CC1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4520	CC1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4532	CC1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1



6.Caution

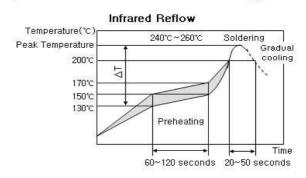
▶ Reflow Soldering

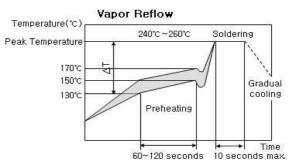
- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference $(\triangle T)$ within the range recommended in Table 1.

Table 1

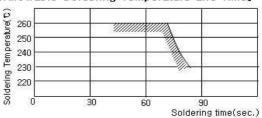
Size code	Temperature Difference
0603, 1005, 1608, 2012, 3216	△T≤190°C
3225size and over	△T≤130°C

[Standard Conditions for Reflow Soldering]





[Allowable Soldering Temperature and Time]



In case of repeated soldering, the accumulated soldering time must be within the range shown above.

► Storage Condition

*When Solderability is considered, Capacitor are recommended to be used in 12 months

(1) Temperature: 25° C ± 10° C

(2) Relative Humidity: Below 70% RH

▶ The Regulation of Environmental Pollution Materials.

*Never use materials mentioned below in MLCC products regulated this document.

Pb, Cd, Hg, Cr⁺⁶, PBB(Polybromide biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos.

* Note

(1) 'Aging'/'De-aging' Behavior of high dielectric MLCCs

(Typically represented by X7R, Y5V temperature characteristic of which main composition is BaTiO3)

'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric Ceramic Capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$$C_t = C_{24} (1 - k \log 10 t)$$

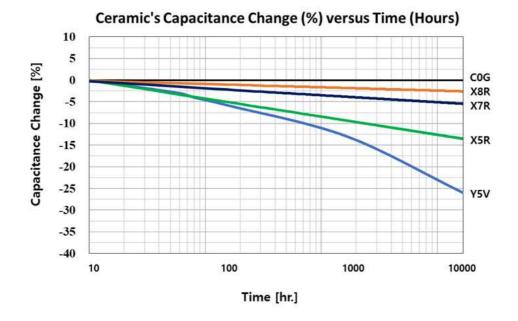
where:

Ct = Capacitance Value, t hours after the start of 'aging'

C₂₄ = Capacitance Value. 24 hours after its manufacture

k = aging constant (capacitance decrease per decade-hour)

t = time, in hours, from the start of 'aging'



The capacitance value can be restored (a.k.a. 'de-aged') by exposing the component to elevated temperatures approaching its Curie Temperature (approximately 120°C). This 'deaging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing., or by 'baking 'at 150°C for about 1 hour.

- (2) Please contact our sales representatives or product engineers before using the products in this catalog for the applications listed below, which require especially high reliability for the prevention of defects which might directly damage a third party's life, body or property, or when one of our products is intended for use in applications other than those specified in this catalog.
 - ①Aircraft equipment
- ②Aerospace equipment
- 3 Undersea equipment

- ©Transportation equipment (vehicles, trains, ships, etc.)
- Traffic signal equipment Spisaster prevention / crime prevention equipment